System for Substrate Processing with Meniscus, Vacuum, IPA vapor, Drying Manifold

ABSTRACT OF THE DISCLOSURE

An apparatus and method for processing a wafer is provided. The system and method are designed to process a surface of a wafer using a meniscus. The meniscus is controlled and is capable of being moved over the surface of the wafer to enable cleaning, rinsing, chemical processing, and drying. The apparatus can be defined using a number of configurations to enable specific processing of the wafer surface using the meniscus, and such configurations can include the use of proximity heads.

Fig. 8A